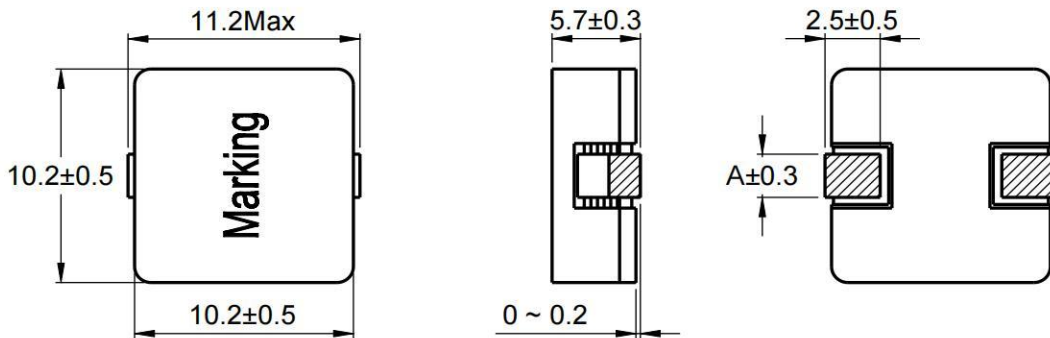


### Outline: 产品概要

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI)  
磁屏蔽结构：抗电磁干扰(EMI)性能强
- Flat wire winding, achieve a low D.C. Resistance.  
扁平线绕组，实现极低的直流电阻。
- Low loss, high efficiency, wide application frequency and application scope.  
低损耗，高效率，应用频率宽，适用范围广。
- Lightweight design, save space, suitable for high density SMT.  
轻薄型设计，节省空间，适合高密度贴装。
- Operating temperature : -55°C ~ +150°C (Including coil's temperature rise)  
工作温度：-55°C ~ +150°C (包含线圈发热)

## 1 Appearance and Dimensions (mm) 外形尺寸 (mm)

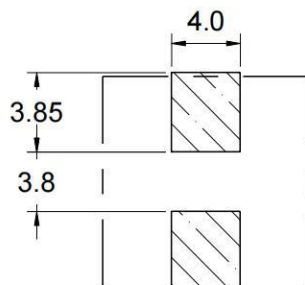


Part No.	R38 - 2R2	2R9 - 270
Dimension A	2.5	2.0

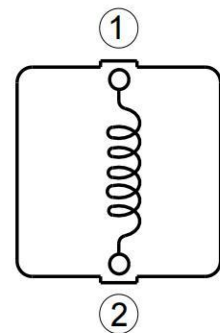
## 2 Marking 印字标识



## 3 Reference Land Pattern (mm) 参考基板尺寸 (mm)



## 4 Schematic 原理图





## 5 Electrical Characteristics

### 电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
YZBX1060-R38M	0.38	0.67	0.77	70.0	25.0
YZBX1060-1R0M	1.00	1.65	1.90	40.0	21.0
YZBX1060-1R5M	1.50	2.47	2.85	34.0	19.0
YZBX1060-2R2M	2.20	3.60	4.20	29.0	16.0
YZBX1060-2R9M	2.90	4.45	5.15	26.0	14.0
YZBX1060-3R8M	3.80	5.89	6.77	22.0	12.0
YZBX1060-4R7M	4.70	7.08	8.15	21.0	10.8
YZBX1060-5R6M	5.60	9.23	10.6	18.0	9.60
YZBX1060-6R8M	6.80	10.9	12.5	16.5	8.70
YZBX1060-8R2M	8.20	13.6	15.6	15.0	7.80
YZBX1060-100M	10.0	16.3	18.7	12.5	6.20
YZBX1060-150M	15.0	20.9	24.0	10.5	5.60
YZBX1060-220M	22.0	31.6	36.3	8.80	4.50
YZBX1060-270M	27.0	42.2	48.5	8.00	4.00

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 100kHz, 0.5V.

电感测试条件为 100kHz, 0.5V。

※2 Saturation current : the actual value of DC current when the inductance decrease 30% of its initial value.

饱和电流 : 电感值下降其初始值的 30% 时所加载的实际直流电流值。

※3 Temperature rise current : the actual value of DC current when the temperature rise is ΔT50°C (Ta=25°C).

温升电流 : 使产品温度上升到 ΔT50°C 时所加载的实际直流电流值 (Ta=25°C)。

※ Special remind : Circuit design, component placement, PCB size and thickness, cooling system and etc.

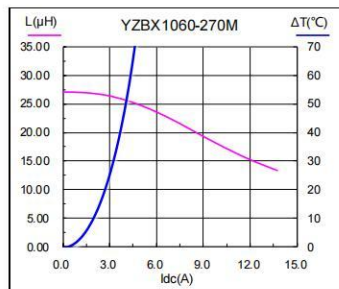
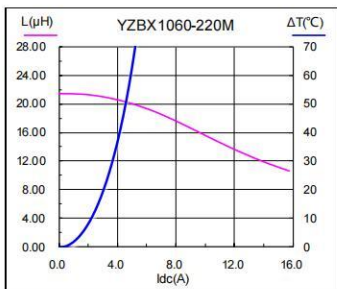
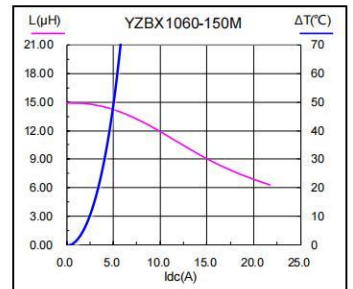
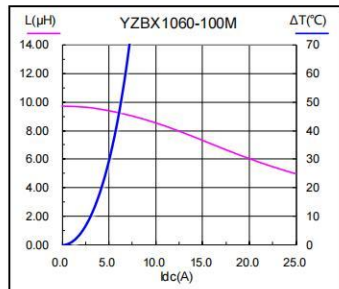
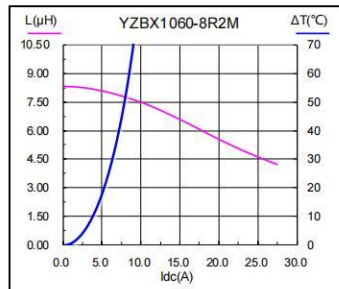
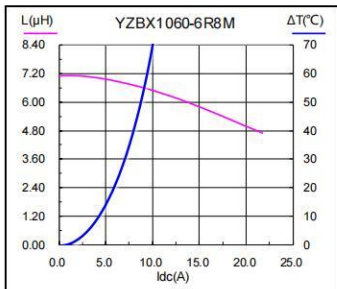
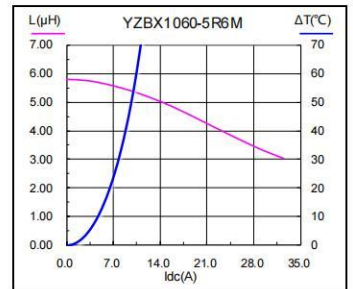
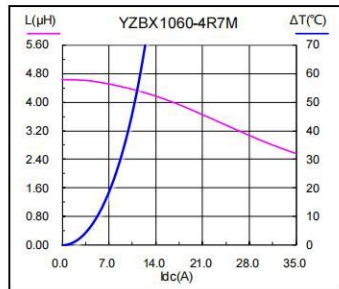
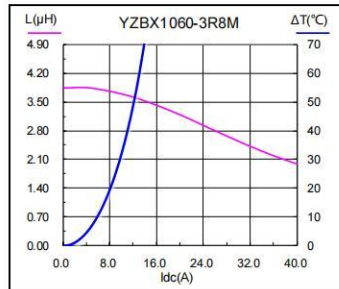
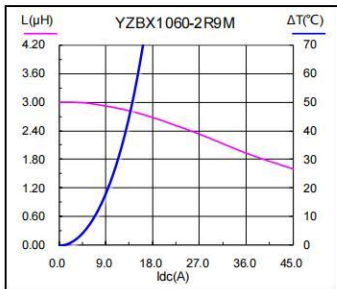
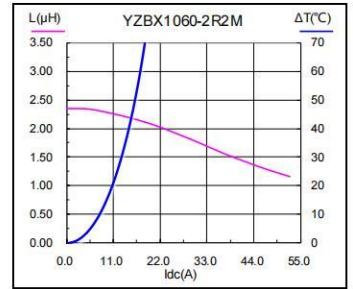
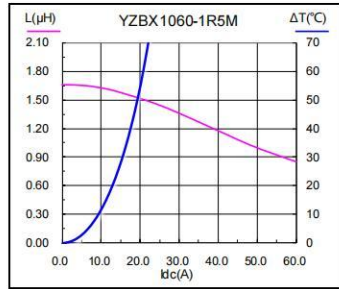
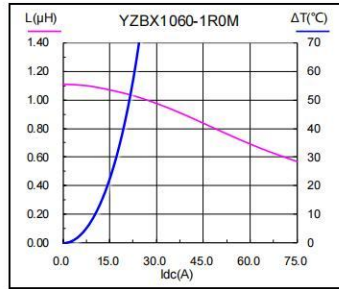
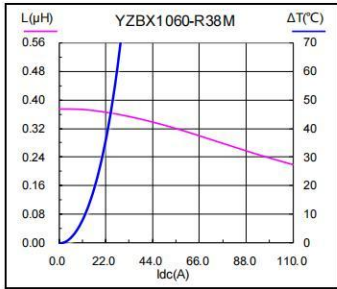
all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒 : 线路设计, 组件布局, 印刷线路板 (PCB) 尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。



### 6 Saturation Current vs Temperature Rise Current Curve 饱和电流 vs 温升电流曲线





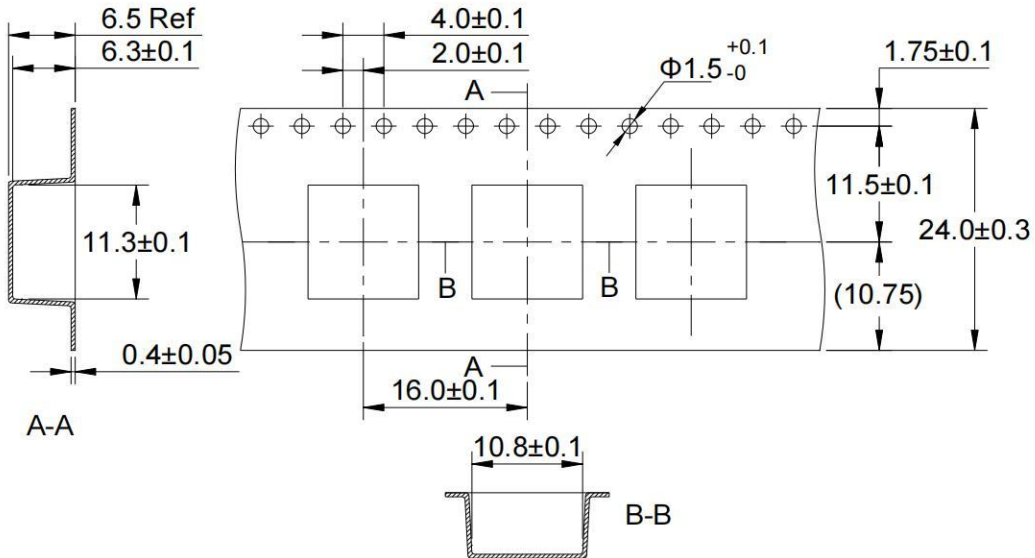


## 7 Packing Specification

### 包装规格

#### 7.1 Carrier Tape Dimensions (mm)

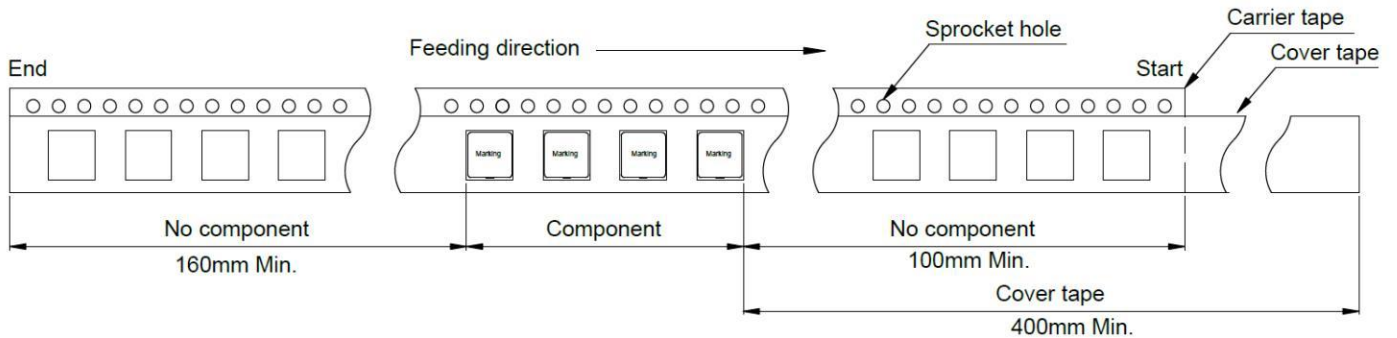
##### 载带尺寸



※ Packing is referred to the international standard IEC 60286-3.  
包装参照国际标准 IEC 60286-3。

#### 7.2 Tape Direction

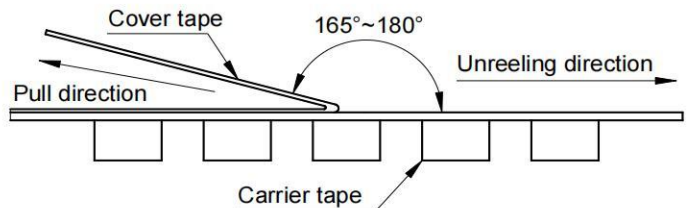
##### 捆包方向



#### 7.3 Cover Tape Peel Off Condition

##### 盖带剥离条件

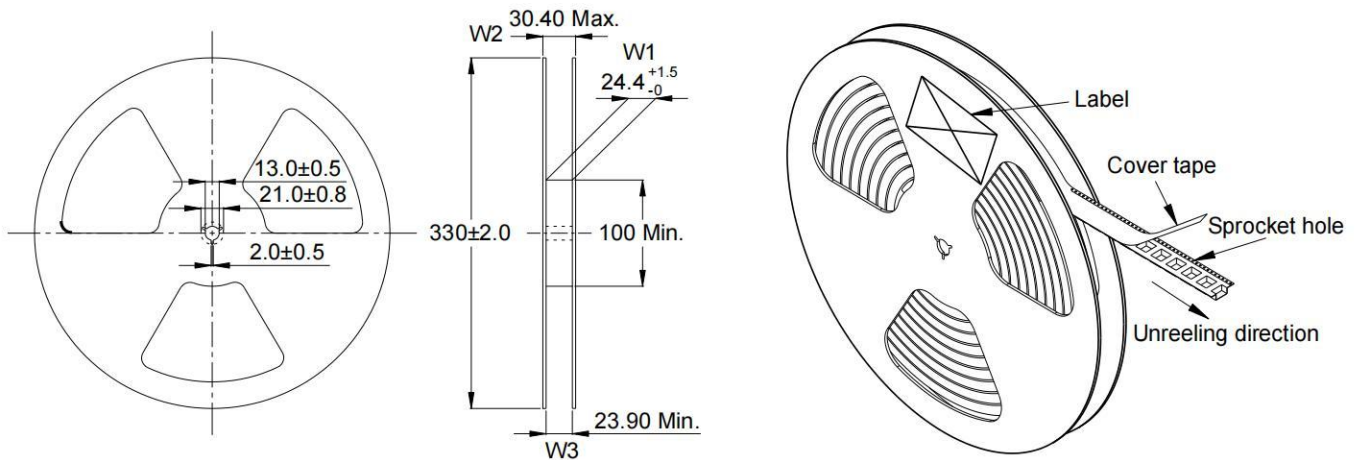
- Cover tape peel force shall be 0.1 to 1.3N.  
盖带剥离力度为 0.1 ~ 1.3N。
- Reference peel speed 300±10mm/min.  
参考剥离速度 300±10mm/分钟。





### 7.4 Reel Dimensions (mm)

卷盘尺寸



### 7.5 Carton Dimensions and Packing Quantity

包装箱尺寸和包装数量

■ Inner Carton : 340×340×95mm  
内包装盒

■ Out Carton : 360×360×370mm  
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
YZBX1060	400pcs	(400×2) = 800pcs	(800×3) = 2400pcs

### 7.6 Label Making

标签标识

The following items will be marked on the reel of product label and shipping label.

以下项目将明确标识于产品卷盘标签以及运输标签上。

#### Production Label

##### 产品标签

- Packing No.  
包装流水号
- Quantity  
数量
- Shipment Date  
出货日期
- Part No.  
产品型号
- Customer Part No.  
客户型号
- Customer Po No.  
客户订单号

#### Shipping Label

##### 运输标签

- Packing No.  
包装流水号
- Quantity  
数量
- Shipment Date  
出货日期
- Part No.  
产品型号
- Customer Part No.  
客户型号
- Customer Po No.  
客户订单号

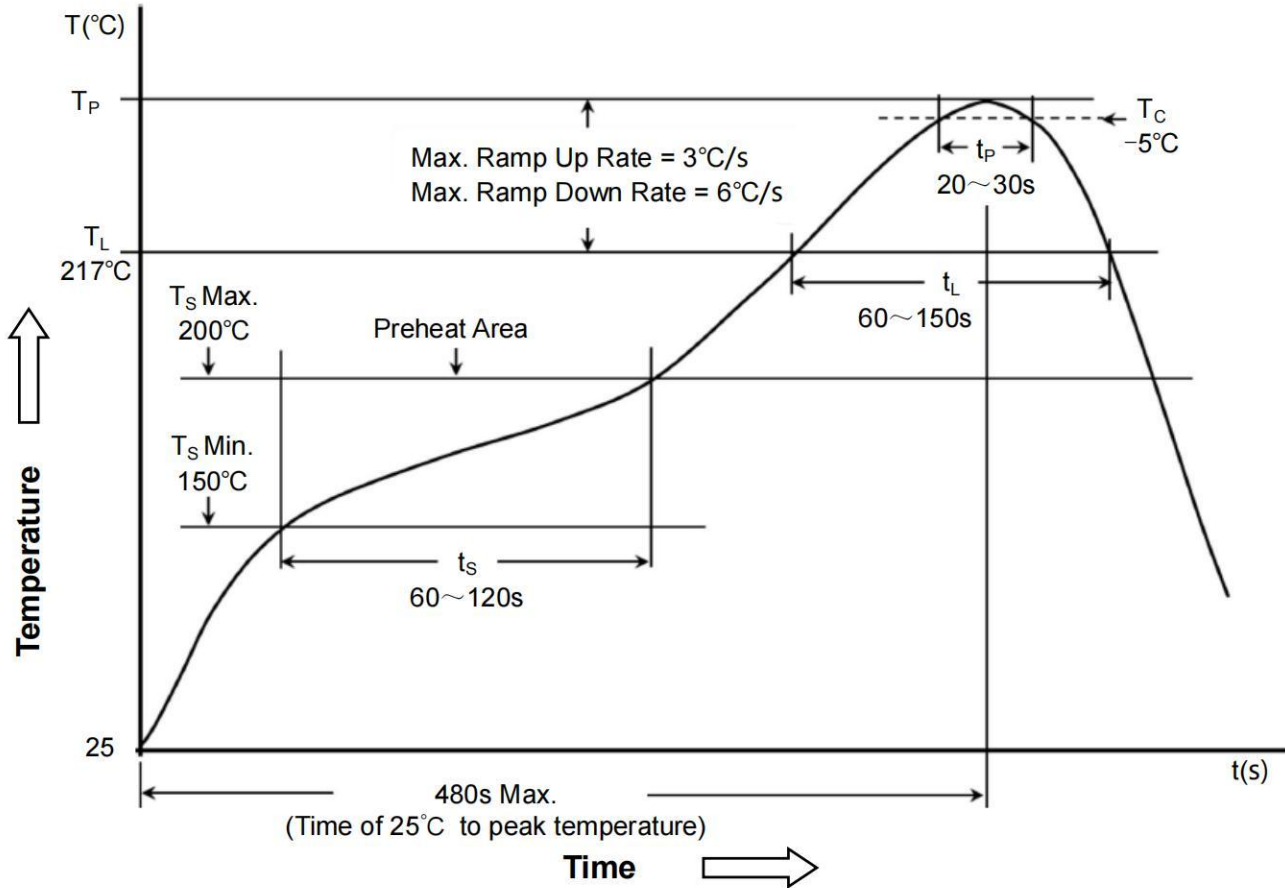


## 8 Soldering specification

### 焊接规格

#### 8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



#### 8.2 Classification of peak package body temperature ( $T_P$ )

封装体峰值温度( $T_P$ )分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		$<350\text{ mm}^3$	$350 \sim 2000\text{ mm}^3$	$>2000\text{ mm}^3$
PB-Free Assembly 无铅装配	$<1.6\text{mm}$	$260^{\circ}\text{C}$	$260^{\circ}\text{C}$	$260^{\circ}\text{C}$
	$1.6 \sim 2.5\text{mm}$	$260^{\circ}\text{C}$	$250^{\circ}\text{C}$	$245^{\circ}\text{C}$
	$\geq 2.5\text{mm}$	$250^{\circ}\text{C}$	$245^{\circ}\text{C}$	$245^{\circ}\text{C}$

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.

回流焊参照标准 IPC/JEDEC J-STD-020D.